2SC4626J

Silicon NPN epitaxial planar type

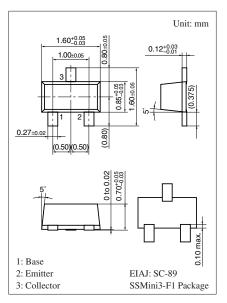
For high-frequency amplification

■ Features

- Optimum for RF amplification of FM/AM radios
- High transition frequency f_T
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit |
|------------------------------|------------------|-------------|------|
| Collector to base voltage | V _{CBO} | 30 | V |
| Collector to emitter voltage | V _{CEO} | 20 | V |
| Emitter to base voltage | V _{EBO} | 5 | V |
| Collector current | I_{C} | 30 | mA |
| Collector power dissipation | P _C | 125 | mW |
| Junction temperature | T _j | 125 | °C |
| Storage temperature | T_{stg} | -55 to +125 | °C |



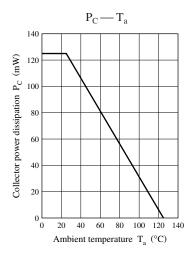
Marking Symbol: V

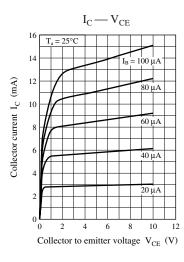
\blacksquare Electrical Characteristics $~T_a = 25^{\circ}C \pm 3^{\circ}C$

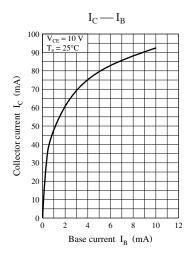
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|-----------------|--|-----|-----|-----|------|
| Collector cutoff current | I_{CBO} | $V_{CB} = 10 \text{ V}, I_E = 0$ | | | 0.1 | μΑ |
| DC current gain * | h _{FE} | $V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}$ | 70 | | 220 | |
| Gain bandwidth product | f_T | $V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$ | 150 | 250 | | MHz |
| Reverse transfer impedance | Z_{rb} | $V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 2 \text{ MHz}$ | | 22 | 50 | Ω |
| Common emitter reverse transfer capacitance | C _{re} | $V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 10.7 \text{ MHz}$ | | 0.9 | 1.5 | pF |
| Noise figure | NF | $V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 5 \text{ MHz}$ | | 2.8 | 4.0 | dB |

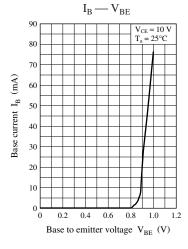
Note) $*: h_{FE}$ rank classification

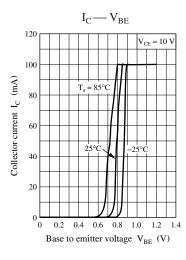
| Rank | В | С | No rank | |
|----------|-----------|------------|-----------|--|
| h_{FE} | 70 to 140 | 110 to 220 | 70 to 220 | |

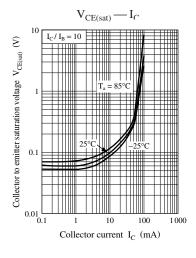


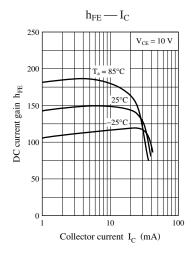


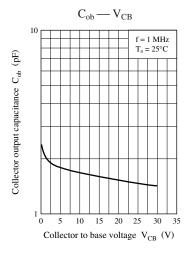












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